# GSE120BB1D3F

# **ESD Protection Diode**

#### **Product Description**

It is designed to protect sensitive electronics from damage due to electrostatic discharge (ESD) and other transient events.

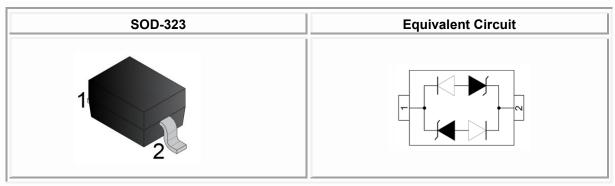
#### **Features**

- Operating Voltage: 12V
- IEC61000-4-2(ESD) ±30kV (Air)
- IEC61000-4-2(ESD) ±30kV (Contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns).
- IEC61000-4-5 (Lightning) 12A (8/20µs).

#### **Mechanical Data**

- SOD-323. Package
- RoHS Compliant and Halogen Free

#### **Package and Pin Assignment**





# **Ordering and Marking Information**

| GS P/N Package  |                              | Marking     | Quantity / Reel |  |
|---|------------------------------|-------------|-----------------|--|
| GSE120BB1D3F  | SOD-323                      | AB 🖯        | 3,000PCS        |  |
| GSE120BB1D3F  - Product Code: GSE120BB1  - Package Code: D3 for SOD-323  - Green Level: F for RoHS Compliant and Halogen Free |                              |             |                 |  |
|   | Marking                      | Information |                 |  |
| AB 🗎  | - Product Code AB - GS Code: | <b>9</b> :  |                 |  |

### Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise specified)

| Symbol           | Parameter                                 | Value       | Unit |
|------------------|---|-------------|------|
| P <sub>PP</sub>  | Peak Pulse Power (t <sub>P</sub> =8/20µs) | 350         | W    |
| IPP              | Peak Pulse Current (t⊳=8/20µs)            | 12          | Α    |
|                  | ESD Per IEC61000-4-2 (Air)                | ±30         | KV   |
| VESD             | ESD Per IEC61000-4-2 (Contact)            | ±30         | KV   |
| TJ               | Operating Junction Temperature Range      | -55 to +125 | °C   |
| T <sub>STG</sub> | Storage Temperature Range                 | -55 to +150 | °C   |

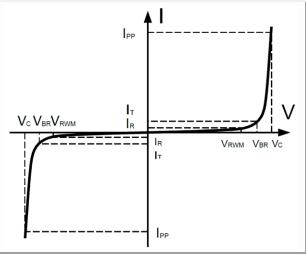


#### Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise specified)

| Symbol                          | Parameter                     | Conditions                   | Min  | Тур  | Max | Unit |
|---------------------------------|-------------------------------|------------------------------|------|------|-----|------|
| V <sub>RWM</sub>                | Reverse Working<br>Voltage    | -                            |      |      | 12  | V    |
| $V_{BR}$                        | Breakdown Voltage             | I <sub>T</sub> = 1mA         | 13.3 |      |     | V    |
| I <sub>R</sub>                  | Reverse Leakage<br>Current    | V <sub>RWM</sub> =12V        |      |      | 1   | μA   |
| .,                              | Q1                            | I <sub>PP</sub> =1A (8/20μs) |      |      | 19  | V    |
| V <sub>C</sub> Clamping Voltage | I <sub>PP</sub> =12A (8/20μs) |                              |      | 28.6 | V   |      |
| Сл                              | Junction Capacitance          | V <sub>R</sub> =0V, f=1MHz   |      | 0.8  |     | pF   |

#### **Electrical Parameters**

| Symbol           | Parameter                                  |  |
|------------------|--|--|
| Ірр              | Reverse Peak Pulse Current                 |  |
| Vc               | Clamping Voltage @ IPP                     |  |
| V <sub>RWM</sub> | Reverse Stand-Off Voltage                  |  |
| I <sub>R</sub>   | Reverse Leakage Current @ V <sub>RWM</sub> |  |
| V <sub>BR</sub>  | Breakdown Voltage @ I⊤                     |  |
| I <sub>T</sub>   | Test Current                               |  |





#### **Typical Characteristics** (T<sub>A</sub>=25° unless otherwise specified)

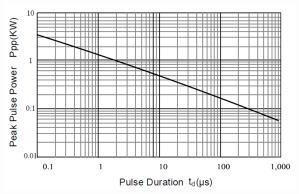


Fig 1. Peak Pulse Power vs. Pulse Time

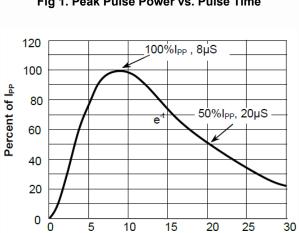


Fig 3. 8 X 20µs Pulse Waveform

Time (µs)

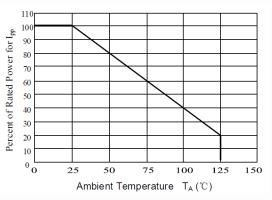


Fig 2. Power Derating Curve

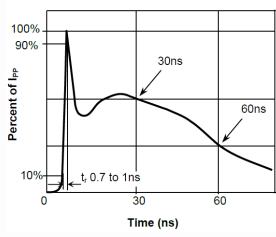


Fig 4. ESD(IEC61000-4-2) Pulse Waveform

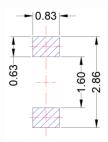


# **SOD-323**

# **Package Dimension**

# GAUGE PLANE

#### **Recommended Land Pattern**



Unit:mm

|         | Dimensions  |      |        |       |  |
|---------|-------------|------|--------|-------|--|
| Oh. a.l | Millimeters |      | Inches |       |  |
| Symbol  | MIN         | MAX  | MIN    | MAX   |  |
| Α       |             | 1.16 |        | 0.046 |  |
| A1      | 0.00        | 0.14 | 0.000  | 0.006 |  |
| A2      | 0.80        |      | 0.031  |       |  |
| b       | 0.25        | 0.40 | 0.010  | 0.016 |  |
| С       | 0.08        | 0.25 | 0.003  | 0.010 |  |
| D       | 1.15        | 1.40 | 0.045  | 0.055 |  |
| Е       | 2.30        | 2.80 | 0.091  | 0.110 |  |
| E1      | 1.40        | 1.80 | 0.055  | 0.071 |  |
| L       | 0.08        |      | 0.003  |       |  |
| θ       | 0°          | 8°   | 0°     | 8°    |  |

#### NOTE:

Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.



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